<table>
<thead>
<tr>
<th>ALL ARTWORK VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP208L8</th>
<th>REV: A</th>
<th>SVN REV: Not In VersionControl</th>
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<tbody>
<tr>
<td>LAYER NAME = Top Solder</td>
<td>TID #: PMP208L8</td>
<td></td>
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</tr>
<tr>
<td>PLOT NAME = Top Solder Mask</td>
<td>GENERATED: 3/29/2017 1:09:01 PM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
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